

HVC142A

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0422-0100

(Previous: ADE-208-1588)

Rev.1.00 Nov 26, 2004

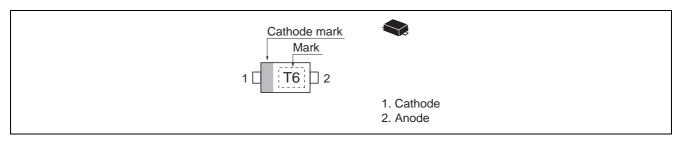
Features

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C = 0.35 pF max)
- Low forward resistance. (rf = $1.3 \Omega \text{ max}$)
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC142A	T6	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Reverse voltage	V_R	30	V
Forward current	I _F	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

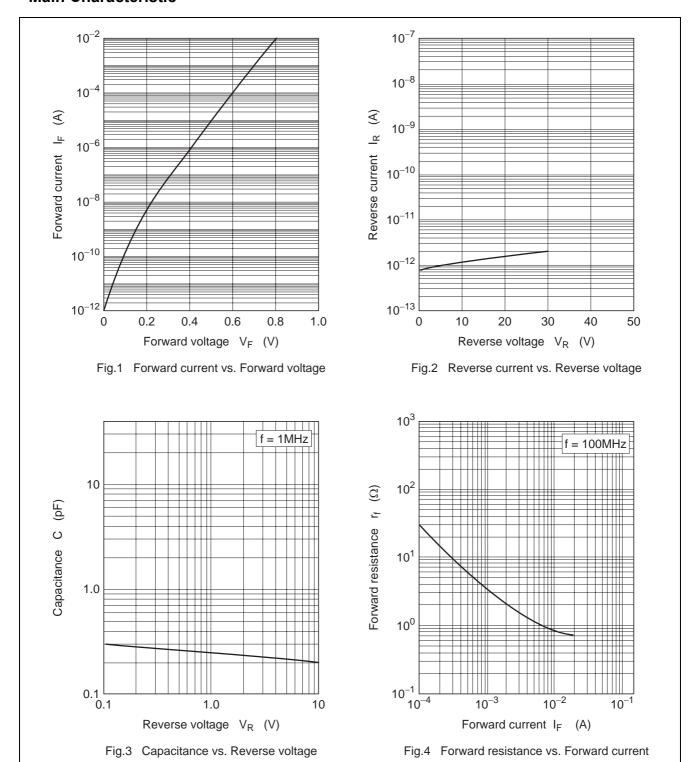
Electrical Characteristics

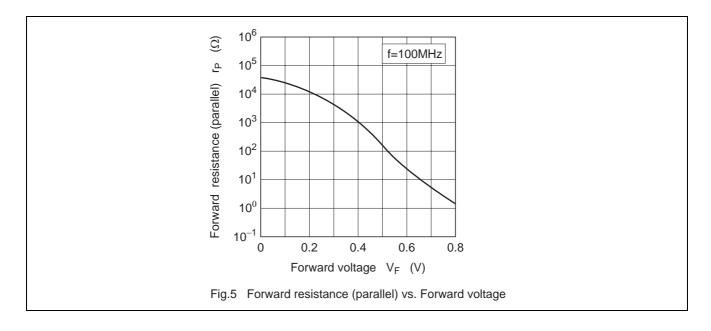
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nA	V _R = 30 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	0.35	pF	V _R = 1 V, f = 1 MHz
Forward resistance	r _f	_	_	1.3	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *1	_	100	_	_	V	C = 200 pF, R = 0 Ω , Both forward
						and reverse direction 1 pulse.

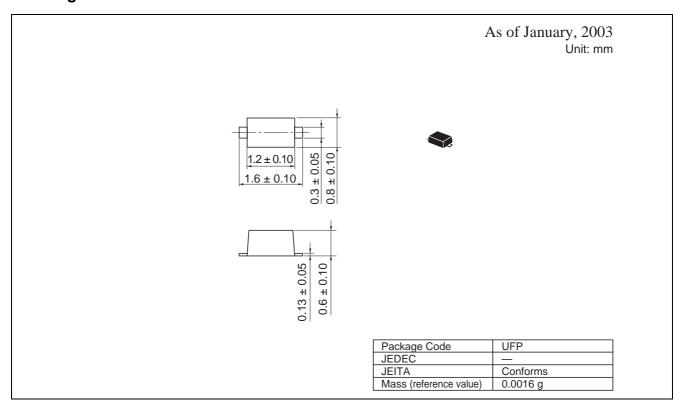
Note: 1. Failure criterion; $I_R > 100$ nA at $V_R = 30$ V

Main Characteristic





Package Dimensions



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